

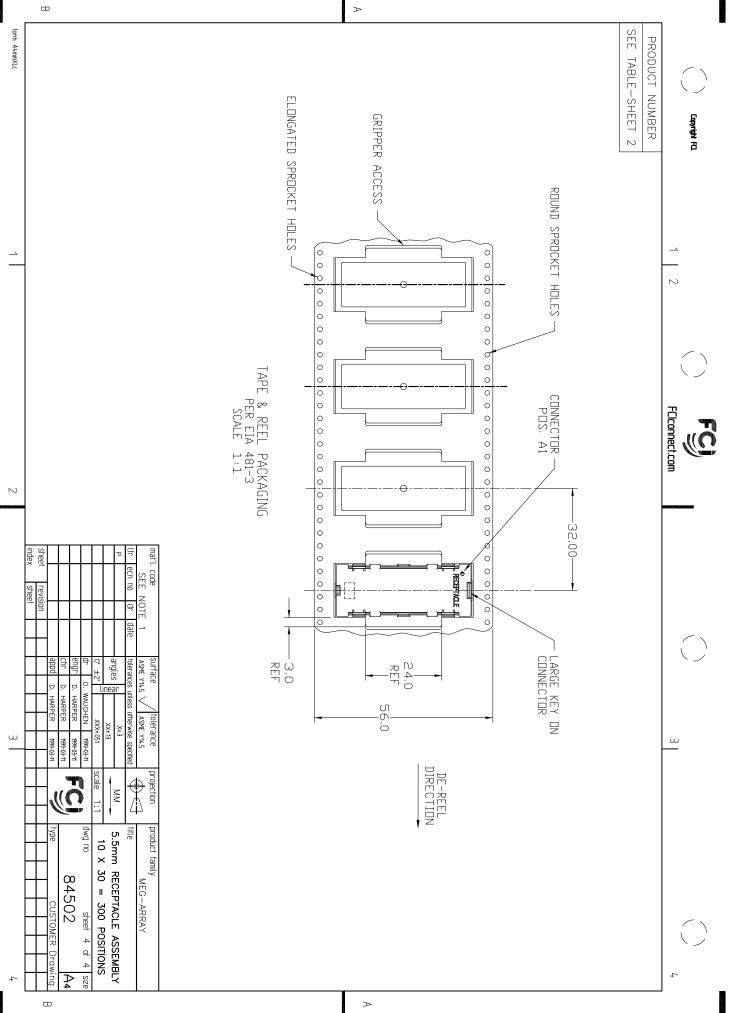
STATUS:Released

PDS: Rev :P

Printed shun 16, 201

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36.83	STEE	NOTE 1 dr date dr date dr date dr date dr to www	mai'l. code SEE NO P ecn no P ecn no		FLAT AREA FOR		
42.30 REF		44.10 REF	5,7	LEAD FREE		YES	84502-A01LF
			7	SnPb		YES	84502-A01
			5,6	LEAD FREE		YES	84502-291LF
	000000000000000000000000000000000000000		σ	SnPb	(1.27,µm)	YES	84502-291
	000000000000000000000000000000000000000	1.27	5,6	LEAD FREE	(1.27µm)	YES	84502-201LF
	00000000		<del>თ</del> თ	SnPb	<u>зоµ (0.76µm) GXI</u> 50µ" (1.27µm) Au SPECIAL	YES	84502-191LF 84502-201
	REF		I			YES	84502-191
	<u>1,c/    - 7,50   / / / / / / / / / / / / / / / / / </u>	POS A1	U	LEAD FREE	(0.76µm)	YES	84502-101LF
-STENCIL MATED CONNECTOR OUTLINE	11.43		(	SnPb	30µ" (0.76µm) Au	YES	84502-101
			л			WITH VENT HOLES	84502-091BF
			ۍ ا	LEAD FREE	15µ" (0.38µm) GXT	YES	84502-091LF
				SnPb	15µ" (0.38µm) GXT	YES	84502-091
			ъ	LEAD FREE	15µ" (0.38µm) Au	YES	84502-001LF
				SnPb	15µ" (0.38µm) Au	YES	84502-001
leased			NOTES	SOLDER BALL	CONTACT PLATING AND THICKNESS	PICK-UP CAP (NATURAL OR BLACK COLOR)	PRODUCT NUMBER
( +-	ω	(		FClconnect.com	2		(
				<u>(</u>	( )	Capyright FCL	) F
n 16, 2							

	8		>	$\backslash$
form: A4mmXLc	<ul> <li>SOLDER REFLOW PROFILE, &amp; SOLDER P</li> <li>(4) KNIT LINE: SLIGHT VISIBLE MARKS (USUA THE DIRECTION AND MEETING POINT OF FRONTS TRAVELING AROUND ANY OBSTRU FLOW VIA THE REQUIRED MOLD TOOLING.</li> <li>(5) FOR PROPER APPLICATION FOLLOW FOL A SPECIFICATION GS-20-033 LEAD FREE S NOT SOLDER PROPERLY IN A LEADED SO DUE TO A HIGHER REFLOW TEMPERATURE PRODUCT IS THERFORE NOT BACKWARDS LEADED OR SOME SOLDERING APPLICATION FCI APPLICATION SPECIFICATION</li> <li>(6) THIS PRODUCT MEETS EUROPEAN UNION OTHER COUNTRY REGULATIONS AS DESCEP RODUCT NUMBER MARKED ON EACH PART I IN THE SEVENTH CHARACTER POSITION.</li> </ul>	2. SOLDER BALLS WILL NO 3. MATED HEIGHT EFFECT	PRODUCT NUMBER SEE TABLE-SHEET 2 NOTES: NOTES: MATERIAL: MATERIAL: PLATING: CONTACT: COPPER ALLOY PLATING: CONTACT: (SEE TABLE ON SOLDER BALL: (SEE TABLE ON 95.55n/4Ag/0.5Cu	Copyright FC
	PASTE. PASTE. PLASTIC RESIN FLO PLASTIC RESIN FLO PLOSTIC RESIN FLO PPLICATION SOLDER PROCESS RE. LEAD FREE WITH SOLDER FREE WITH SOLDER PROCESS RE. LEAD FREE WITH SOLDER PROCESS RE. LEAD FREE WITH SOLDER PROCESS RE. LEAD FREE WITH SOLDER PROCESS RE. LEAD FREE TH SOLDER PROCESS RE. LEAD FREE WITH SOLDER SALLS COMPATIBLE WITH SOLDER ALLS SOLDER ALLS SOLDER BALLS SOLDER PROCESS RE. LEAD FREE WITH SOLDER SOLDER BALLS SOLDER PROCESS RE. LEAD FREE WITH SOLDER BALLS SOLDER PROCESS RE. LEAD FREE WITH SOLDER THE ALLS SOLDER ALLS SOLDER THE ALLS SOLDER	2) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT. 3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING,	REF TEIGHT HEIGHT HEIGHT AFTER REFLOW IS AND .13mm SOLDER PASTE E ON SHEET 2) FREE E ON SHEET 2)	્ ,્(દ
	MOTE WHICH HAS B matt. code utr ecn n sheet index	(9) CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN. 10. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR	<pre>ametical and a second and a second a second</pre>	



PDS: Rev :P STA

STATUS:Released Printeds Jun 1

, 2016

## **Mouser Electronics**

Authorized Distributor

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FCI / Amphenol:

84502-A01LF 84502-191LF 84502-191 84502-291 84502-091